oe-a PRODUCTS & SERVICES DIRECTORY

Products & Services Directory

OE-A members: A – Em (1 of 2)

Categories: Region – Devices

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	Region					Core Competence							Substrates				
	Africa	Asia	Oceania	Europe	North America	Material supplier	Equipment manufacturer	Device manufacturer	Consulting & other services	End-user	R&D Institute	University	paper	plastic	metal	stainless steel	glass
2D ApS DTU Skylab				●		●											
ABeetle Corporation		●						●						●			
Ailarian Ltd.				●		●											
AlmaScience				●							●		●	●			
Almax					●			●									
Alper S.R.L.				●				●						●			
Alqio				●				●									
Amires S.R.O.				●					●								
Aristotle University of Thessaloniki LTFN				●								●		●			●
Bayflex Solutions LLC					●		●										
BeFC SAS				●				●									
Beneli AB				●		●		●					●	●			
BotFactory Inc.					●		●										
Brendle Metalquimica S.A.				●		●											
Brewer Science, Inc.					●			●						●			
BRNO University of Technology				●								●		●			●
BST GmbH				●			●		●								
BW Papersystems Stuttgart GmbH				●			●										
California Polytechnic State University					●							●					
CCI Eurolam GmbH				●			●						●	●			
CEA LITEN				●							●		●	●			●
CeNTI - Centre for Nanotechnoloy & Smart Materials				●							●		●	●	●	●	●
Centre Microélectronique de Provence																	
École Nationale Supérieure des Mines				●							●						
Chasinglight		●						●									
CIDETEC				●							●		●	●			●
Consiglio Nazionale delle Ricerche (CNR)				●							●			●	●		●
CondAlign AS				●			●										
ContiTech Deutschland GmbH				●				●									
Copprint Technologies Ltd.		●					●						●	●	●		●
CPI - Centre for Process Innovation				●							●		●	●			●
CSEM				●							●						
CSIR Council for Scientific and Industrial Research - DST Nano-Micro Manufacturing Facility	●										●	●	●	●			●
CurveSYS GmbH				●				●									
Dai Nippon Printing Co., Ltd. (JP)		●					●						●	●	●	●	●
Danish Technological Institute				●							●						
db-matik AG				●				●						●	●		
DOMICRO BV				●				●	●				●	●	●	●	●
Dorey Converting Systems				●			●										
DP Patterning AB				●				●									
Dracula Technologies				●				●									
E INK Corporation					●			●									
Eindhoven University of Technology				●								●					
Elantas Europe GmbH				●			●										
EMPA				●							●						

	Materials										Encapsulation						Equipment / Processes																				Devices							
	textiles	other substrates	organic conductor	inorganic conductor / metal	p-type organic semiconductor	n-type organic semiconductor	inorganic semiconductor	dielectric	carbon nanotubes	graphene	other materials	thin film encapsulation	polymer film encapsulation	metal encapsulation	glass encapsulation	resins	other encapsulation	gravure printing	offset printing	flexographic printing	screen printing (flat bed)	inkjet printing	other printing	PVD - evaporation	PVD - sputtering	organic vapor phase deposition	spin coating	other coating (dip, blade, ...)	photolithography	laser ablation	laser transfer	encapsulation	clean room	ink formulation & manufacturing	dosing, metering & mixing of inks and fluids	other equipment / processes	transistors	memory elements	diodes	antennas	passives (e.g. capacitors, resistors)	integrated circuits (ICs)
2D ApS DTU Skylab																																									
ABeetle Corporation		●						●	●	●	●		●			●					●											●								●
Ailarian Ltd.																																									
AlmaScience		●	●	●	●		●	●			●		●							●	●	●	●	●		●	●	●	●		●	●	●	●		●	●		●	●	●
Almax																																									
Alper S.R.L.								●				●	●								●											●		●							
Alqio																																									
Amires S.R.O.																																									
Aristotle University of Thessaloniki LTFN	●		●	●	●	●		●				●	●					●				●	●	●	●	●	●		●		●	●				●				●
Bayflex Solutions LLC																																			●						
BeFC SAS																																									
Beneli AB		●						●																								●			●			●		
BotFactory Inc.																																									
Brendle Metalquimica S.A.																																									
Brewer Science, Inc.		●	●	●	●			●	●	●	●	●	●			●	●	●		●	●	●		●		●	●	●	●		●	●	●	●	●					●	
BRNO University of Technology	●		●	●	●	●														●	●	●		●		●					●			●	●		●			
BST GmbH																		●	●	●	●		●				●	●			●										
BW Papersystems Stuttgart GmbH																																									
California Polytechnic State University																																									
CCI Eurolam GmbH			●	●			●	●		●			●							●	●						●					●						●	●	
CEA LITEN			●		●	●		●					●					●		●			●	●		●		●		●					●		●	●	●
CeNTI - Centre for Nanotechnoloy & Smart Materials	●		●	●			●	●	●			●	●	●		●		●		●			●	●		●		●		●	●	●	●				●	●	●
Centre Microélectronique de Provence																																									
École Nationale Supérieure des Mines																																									
Chasinglight																																									
CIDETEC	●		●	●	●	●	●	●	●	●						●				●	●		●	●		●	●		●				●	●						●
Consiglio Nazionale delle Ricerche (CNR)			●	●	●	●	●	●	●	●		●		●								●	●	●	●	●	●	●		●	●				●	●	●			
CondAlign AS																																									
ContiTech Deutschland GmbH																																									
Copprint Technologies Ltd.				●														●		●	●			●										●					●		
CPI - Centre for Process Innovation	●	●	●	●	●	●	●	●	●	●	●	●	●		●	●	●	●		●	●	●	●	●	●	●	●	●		●	●	●	●	●	●	●		●	●	●
CSEM													●	●	●			●		●	●		●	●		●	●	●		●	●				●		●	●			
CSIR Council for Scientific and Industrial Research - DST Nano-Micro Manufacturing Facility				●						●									●	●	●					●	●													
CurveSYS GmbH																																									
Dai Nippon Printing Co., Ltd. (JP)		●		●				●				●	●	●				●	●					●	●			●									●		●	●	
Danish Technological Institute				●				●		●										●	●								●					●							
db-matik AG						●	●													●	●			●			●			●				●			●	●		●	●
DOMICRO BV	●	●	●	●	●	●	●	●		●		●	●								●											●			●	●	●	●	●	●
Dorey Converting Systems																																			●						
DP Patterning AB																																									
Dracula Technologies																																									
E INK Corporation																																									
Eindhoven University of Technology																																									
Elantas Europe GmbH				●				●		●											●											●	●	●	●				●		
EMPA			●						●		●	●						●		●	●		●	●		●	●		●											

Products & Services Directory

OE-A members: A – Em (2 of 2)

Categories: Devices – Education

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	Devices												Integration				
	OLEDs	electrochromic displays	electrophoretic displays	electroluminescence	bioluminescence	other display technologies	touch screens / surfaces	sensors (devices)	photovoltaic cells	OPV - organic photovoltaic cells	batteries	other devices	hybrid systems	electrical contacting (e.g. flip-chip)	lamination	integration into packaging	other (integration)
2D ApS DTU Skylab																	
ABeetle Corporation						●	●	●					●		●		
Ailarian Ltd.																	
AlmaScience		●		●		●	●	●	●			●	●				
Almax																	
Alper S.R.L.															●		
Alqio																	
Amires S.R.O.																	
Aristotle University of Thessaloniki LTFN	●							●	●						●		
Bayflex Solutions LLC																	
BeFC SAS																	
Beneli AB								●							●		
BotFactory Inc.																	
Brendle Metalquimica S.A.																	
Brewer Science, Inc.								●					●		●	●	●
BRNO University of Technology	●							●	●			●					
BST GmbH																	
BW Papersystems Stuttgart GmbH																	
California Polytechnic State University																	
CCI Eurolam GmbH				●			●	●	●								
CEA LITEN								●					●		●	●	
CeNTI - Centre for Nanotechnoloy & Smart Materials	●	●		●			●	●	●	●	●		●	●	●	●	
Centre Microélectronique de Provence																	
École Nationale Supérieure des Mines																	
Chasinglight																	
CIDETEC		●				●	●	●	●		●		●		●	●	
Consiglio Nazionale delle Ricerche (CNR)	●			●		●		●	●		●					●	
CondAlign AS																	
ContiTech Deutschland GmbH																	
Copprint Technologies Ltd.						●		●	●		●						
CPI - Centre for Process Innovation	●			●		●	●	●	●	●	●	●	●	●	●	●	●
CSEM	●						●	●	●						●		
CSIR Council for Scientific and Industrial Research -																	
DST Nano-Micro Manufacturing Facility													●				
CurveSYS GmbH																	
Dai Nippon Printing Co., Ltd. (JP)															●		
Danish Technological Institute								●				●	●				
db-matik AG	●	●	●	●		●	●	●						●	●	●	
DOMICRO BV	●						●	●			●	●				●	●
Dorey Converting Systems															●		●
DP Patterning AB																	
Dracula Technologies																	
E INK Corporation																	
Eindhoven University of Technology																	
Elantas Europe GmbH				●				●		●	●	●					
EMPA													●	●			

	Testing								Applications by Industry										Applications												Other Services			Education		
	electrical characterization	physical/optical characterization	chemical characterization	lifetime	quality / process control	environmental testing	simulation / circuit optimization	other tests	automotive	consumer electronics	healthcare, medical and pharmaceutical	sports goods, wellbeing	lighting (applications by industry)	energy	building and architecture	retail and logistics	textiles and fashion	printing and graphic arts	packaging	other applications by industry	sensors (applications)	displays	lighting (applications)	transistors	solar cells	smart objects (e.g. smart cards, games, gadgets)	RFID	speakers	smart textiles	wearables	other applications	technical consulting	business consulting	management of R&D funding programs	research and development	Bachelor/Master Thesis	PhD Thesis	Internship
2D ApS DTU Skylab																																				
ABeetle Corporation	●	●		●	●	●			●	●	●	●	●		●		●	●		●	●	●	●			●			●	●				●			
Ailarian Ltd.																																				
AlmaScience	●	●	●				●			●	●	●		●	●	●	●	●	●		●	●		●	●	●	●		●	●		●	●	●	●	●	●
Almax																																				
Alper S.R.L.				●	●				●	●	●	●			●					●	●												●	●	●		
Alqio																																				
Amires S.R.O.									●	●	●	●	●	●	●	●	●	●	●	●														●	●	
Aristotle University of Thessaloniki LTFN	●	●	●	●	●		●				●		●	●			●		●		●	●	●	●	●				●			●	●			
Bayflex Solutions LLC	●	●		●	●	●	●		●	●	●	●	●	●	●	●	●	●	●	●	●	●	●			●	●		●	●	●	●				
BeFC SAS																																				
Beneli AB					●				●		●				●												●			●		●				
BotFactory Inc.																																				
Brendle Metalquimica S.A.																																				
Brewer Science, Inc.	●	●	●	●	●	●	●	●	●	●		●			●			●	●	●	●	●		●	●	●			●	●			●	●	●	●
BRNO University of Technology	●	●	●	●		●			●	●	●	●								●					●				●	●						
BST GmbH					●		●		●	●	●			●				●	●	●											●	●		●	●	●	●
BW Papersystems Stuttgart GmbH																																				
California Polytechnic State University																																				
CCI Eurolam GmbH									●	●	●	●	●				●		●		●	●	●		●	●	●	●	●	●						
CEA LITEN	●	●	●	●					●	●	●	●	●	●		●			●		●	●	●		●	●		●	●	●				●	●	
CeNTI - Centre for Nanotechnoloy & Smart Materials	●	●	●			●	●	●	●	●	●	●	●	●	●	●		●		●	●	●	●		●	●	●	●	●	●		●		●		●
Centre Microélectronique de Provence																																				
École Nationale Supérieure des Mines																																				
Chasinglight																																				
CIDETEC	●	●	●			●	●	●	●	●	●	●	●	●	●	●		●	●	●	●	●	●		●	●		●	●				●		●	●
Consiglio Nazionale delle Ricerche (CNR)	●	●	●	●	●	●	●		●	●	●		●	●					●		●	●	●	●	●		●		●			●		●		
CondAlign AS																																				
ContiTech Deutschland GmbH																																				
Copprint Technologies Ltd.									●	●	●		●	●				●	●		●	●	●		●	●	●			●						
CPI - Centre for Process Innovation	●	●	●	●	●	●	●	●			●	●	●	●		●	●	●	●	●	●	●	●	●	●	●		●	●	●	●	●	●	●		●
CSEM	●	●		●	●	●	●			●	●		●	●		●	●		●		●	●	●	●	●	●		●			●	●		●			
CSIR Council for Scientific and Industrial Research -																																				
DST Nano-Micro Manufacturing Facility	●	●	●							●	●									●										●				●		●	
CurveSYS GmbH																																				
Dai Nippon Printing Co., Ltd. (JP)									●	●	●			●	●			●																			
Danish Technological Institute	●	●	●	●	●	●		●													●		●				●		●	●		●		●	●	●
db-matik AG	●				●		●		●	●	●		●								●		●				●		●	●		●		●	●	●
DOMICRO BV									●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●		●	●	●
Dorey Converting Systems				●					●	●	●	●		●		●		●	●		●	●		●	●	●	●		●	●	●	●				
DP Patterning AB																																				
Dracula Technologies																																				
E INK Corporation																																				
Eindhoven University of Technology																																				
Elantas Europe GmbH	●	●	●	●	●	●		●	●	●	●	●	●	●	●	●	●	●	●	●		●		●	●	●	●		●			●	●	●	●
EMPA	●	●	●	●			●	●	●	●	●	●	●	●	●		●		●	●	●												●	●	●	●

oe-a PRODUCTS & SERVICES DIRECTORY

Products & Services Directory

OE-A members: Eu – I (1 of 2)

Categories: Region – Devices

www.oe-a.org

	Region					Core Competence							Substrates				
	Africa	Asia	Oceania	Europe	North America	Material supplier	Equipment manufacturer	Device manufacturer	Consulting & other services	End-user	R&D Institute	University	paper	plastic	metal	stainless steel	glass
Eurecat				●							●		●	●			
European Space Agency, ESA/ECSAT				●							●						
Exakt Advanced Technologies GmbH				●			●										
Felix Böttcher GmbH & Co. KG				●			●										
Felix Schoeller Holding GmbH & Co. KG				●		●							●	●			
FlexEnable Technology Ltd				●		●		●									
Flexoo GmbH				●				●					●	●			
Folex Coating GmbH				●		●								●			
Fontys University of Applied Sciences				●								●	●	●			●
Fraunhofer Reserarch Institution for Microsystems and Solid State Technologies EMFT				●							●		●	●			
Fraunhofer ENAS				●							●		●	●	●		●
Fraunhofer FEP				●				●			●		●	●	●	●	●
Fraunhofer IAP				●							●		●	●	●		●
Fraunhofer IFAM				●							●			●	●	●	●
Fraunhofer ILT				●							●						
Fraunhofer IPA				●							●		●	●	●		●
Fraunhofer ISC				●							●			●			
Fraunhofer ISE				●							●			●	●		●
Friedrich Schiller University Jena				●								●		●	●		●
Fundación Gaiker				●							●						
Fundacion Tekniker				●							●			●			
Genes´Ink				●			●						●	●	●		●
GraphenicaLab S.L.				●				●									
H.C. Moog Maschinen für Druck und Papier				●				●					●	●			
Hahn-Schickard-Gesellschaft für angewandte Forschung e.V.				●							●						
Henkel AG & Co.KGaA				●			●										
Heraeus Epurio GmbH				●			●	●					●	●	●		●
Heraeus Printed Electronics GmbH				●			●										
Hochschule der Medien IAF, IAD				●								●	●	●	●		●
Hochschule München University of Applied Sciences				●								●		●			
Hoffmann+Krippner GmbH				●					●					●			
Holst Centre				●							●		●	●			●
Hochschule Niederrhein				●								●					
Hummink				●			●						●	●	●		●
IBS Precision Engineering B.V.				●			●										
IEE S.A. ZAE Weiergewan				●				●									
Imperial College London - Centre for Plastic Electronics				●								●					
Industrial Print Solutions GmbH				●			●										
Innovation Horizons GmbH				●					●								
Ino, d.o.o., Ziri				●			●										
Institut für Mikroelektronik Stuttgart				●							●			●			
Interlink Electronics, Inc.					●	●		●					●	●			
IO Tech - Reophotonics		●					●										
IPC - Technical Centre of Plastics Engineering				●							●			●			
IU Internationale Hochschule				●								●					

		Materials									Encapsulation						Equipment / Processes																				Devices						
	textiles	other substrates	organic conductor	inorganic conductor / metal	p-type organic semiconductor	n-type organic semiconductor	inorganic semiconductor	dielectric	carbon nanotubes	graphene	other materials	thin film encapsulation	polymer film encapsulation	metal encapsulation	glass encapsulation	resins	other encapsulation	gravure printing	offset printing	flexographic printing	screen printing (flat bed)	inkjet printing	other printing	PVD - evaporation	PVD - sputtering	organic vapor phase deposition	spin coating	other coating (dip, blade, ...)	photolithography	laser ablation	laser transfer	encapsulation	clean room	ink formulation & manufacturing	dosing, metering & mixing of inks and fluids	other equipment / processes	transistors	memory elements	diodes	antennas	passives (e.g. capacitors, resistors)	integrated circuits (ICs)
Eurecat	●																●																								
European Space Agency, ESA/ECSAT																																						●	●	●
Exakt Advanced Technologies GmbH				●					●	●	●																						●	●				●	●	
Felix Böttcher GmbH & Co. KG																		●	●	●		●	●					●				●			●					
Felix Schoeller Holding GmbH & Co. KG													●																												
FlexEnable Technology Ltd					●			●																												●	●			●	
Flexoo GmbH	●			●				●	●											●	●	●						●				●							●	
Folex Coating GmbH			●								●																													
Fontys University of Applied Sciences			●	●	●	●																●	●	●	●		●	●							●				●	
Fraunhofer ENAS	●	●	●	●	●	●	●	●	●			●	●	●	●						●	●		●	●		●				●	●	●		●	●		●	●	
Fraunhofer FEP	●	●						●				●	●	●	●		●				●			●	●	●	●			●		●	●			●				●
Fraunhofer IAP	●	●		●	●	●	●	●				●	●		●			●			●	●		●			●	●	●			●	●	●		●		●		
Fraunhofer IFAM	●			●				●		●											●	●		●	●							●	●						●	●
Fraunhofer ILT													●		●							●	●						●	●	●										
Fraunhofer IPA	●	●	●	●				●	●	●	●		●				●		●	●	●	●	●				●	●		●			●	●	●				●	●	
Fraunhofer ISC				●			●	●			●	●			●	●					●	●					●	●	●	●			●	●						●	
Fraunhofer ISE			●	●	●	●	●	●				●	●		●	●					●	●	●	●	●		●	●	●			●	●			●		●			
Friedrich Schiller University Jena		●	●	●	●	●	●	●	●		●											●	●		●		●	●										●	●	●	
Fundación Gaiker																																								
Fundacion Tekniker				●				●	●	●	●	●									●	●		●			●	●			●								●		
Genes´Ink	●	●		●	●	●	●						●					●	●	●	●	●					●	●					●		●	●		●	●	●	●
GraphenicaLab S.L.																																								
H.C. Moog Maschinen für Druck und Papier																		●	●																				●	
Hahn-Schickard-Gesellschaft für angewandte Forschung e.V.															●						●	●	●	●	●		●		●		●	●		●	●		●	●	●
Henkel AG & Co.KGaA																					●	●																		
Heraeus Epurio GmbH	●		●	●											●			●			●	●					●	●		●			●		●			●	●	●
Heraeus Printed Electronics GmbH																																								
Hochschule der Medien IAF, IAD	●	●	●	●				●	●		●	●	●	●	●	●		●	●	●	●	●						●		●				●	●				●	●
Hochschule München University of Applied Sciences	●	●		●	●			●	●	●											●	●															●		●	●
Hoffmann+Krippner GmbH			●	●				●		●											●													●					●	●
Holst Centre	●		●	●			●	●			●	●	●								●	●	●	●	●		●		●	●	●	●			●	●	●	●	●	●	●
Hochschule Niederrhein																																								
Hummink			●	●	●	●	●	●	●	●	●											●												●		●	●		●		●
IBS Precision Engineering B.V.																																								
IEE S.A. ZAE Weiergewan																																								
Imperial College London - Centre for Plastic Electronics																																								
Industrial Print Solutions GmbH																																								
Innovation Horizons GmbH																																								
Ino, d.o.o., Ziri																					●																			
Institut für Mikroelektronik Stuttgart					●	●	●	●	●				●	●								●					●		●			●				●		●	●	●	●
Interlink Electronics, Inc.																●					●								●			●	●						●	
IO Tech - Reophotonics																																								
IPC - Technical Centre of Plastics Engineering	●		●	●				●					●			●	●				●		●				●				●									●
IU Internationale Hochschule																																								

Products & Services Directory

OE-A members: Eu – I (2 of 2)

Categories: Devices – Education

www.oe-a.org

	Devices													Integration				
	OLEDs	electrochromic displays	electrophoretic displays	electroluminescence	bioluminescence	other display technologies	touch screens / surfaces	sensors (devices)	photovoltaic cells	OPV - organic photovoltaic cells	batteries	other devices	hybrid systems	electrical contacting (e.g. flip-chip)	lamination	integration into packaging	other (integration)
Eurecat		●		●				●	●	●			●				●
European Space Agency, ESA/ECSAT																	
Exakt Advanced Technologies GmbH		●				●	●	●	●		●						
Felix Böttcher GmbH & Co. KG																	
Felix Schoeller Holding GmbH & Co. KG																	
FlexEnable Technology Ltd																	
Flexoo GmbH																	
Folex Coating GmbH																	
Fontys University of Applied Sciences	●							●	●								
Fraunhofer Reserarch Institution for Microsystems and Solid State Technologies EMFT				●				●				●		●	●	●	
Fraunhofer ENAS	●										●		●	●	●	●	
Fraunhofer FEP	●					●		●	●	●		●			●		●
Fraunhofer IAP	●	●		●				●	●	●	●				●		
Fraunhofer IFAM											●		●	●	●		
Fraunhofer ILT									●		●			●	●	●	
Fraunhofer IPA	●	●		●		●	●	●			●	●	●	●	●		
Fraunhofer ISC		●					●	●			●						
Fraunhofer ISE		●							●						●		
Friedrich Schiller University Jena	●	●						●	●		●						
Fundación Gaiker																	
Fundacion Tekniker							●	●	●				●				
Genes´Ink	●	●				●	●	●	●	●	●	●	●				
GraphenicaLab S.L.																	
H.C. Moog Maschinen für Druck und Papier																	
Hahn-Schickard-Gesellschaft für angewandte Forschung e.V.								●				●	●	●	●	●	●
Henkel AG & Co.KGaA																	
Heraeus Epurio GmbH	●	●	●	●			●		●	●	●						
Heraeus Printed Electronics GmbH																	
Hochschule der Medien IAF, IAD		●		●		●	●	●	●		●		●	●		●	
Hochschule München University of Applied Sciences		●		●			●	●			●		●	●	●	●	
Hoffmann+Krippner GmbH		●					●	●				●		●	●	●	●
Holst Centre	●	●				●	●	●	●		●	●	●	●	●		●
Hochschule Niederrhein																	
Hummink	●					●		●									
IBS Precision Engineering B.V.																	
IEE S.A. ZAE Weiergewan																	
Imperial College London - Centre for Plastic Electronics																	
Industrial Print Solutions GmbH																	
Innovation Horizons GmbH																	
Ino, d.o.o., Ziri																	
Institut für Mikroelektronik Stuttgart								●					●		●	●	●
Interlink Electronics, Inc.							●	●									
IO Tech - Reophotonics																	
IPC - Technical Centre of Plastics Engineering							●	●				●	●		●	●	●
IU Internationale Hochschule																	

oe-a PRODUCTS & SERVICES DIRECTORY

	Testing								Applications by Industry										Applications											Other Services				Education		
	electrical characterization	physical/optical characterization	chemical characterization	lifetime	quality / process control	environmental testing	simulation / circuit optimization	other tests	automotive	consumer electronics	healthcare, medical and pharmaceutical	sports goods, wellbeing	lighting (applications by industry)	energy	building and architecture	retail and logistics	textiles and fashion	printing and graphic arts	packaging	other applications by industry	sensors (applications)	displays	lighting (applications)	transistors	solar cells	smart objects (e.g. smart cards, games, gadgets)	RFID	speakers	smart textiles	wearables	other applications	technical consulting	business consulting	management of R&D funding programs	research and development	Bachelor/Master Thesis	PhD Thesis	Internship
Eurecat									●	●	●	●		●	●	●	●	●	●		●		●		●	●		●	●		●		●	●	●	
European Space Agency, ESA/ECSAT																																				
Exakt Advanced Technologies GmbH								●	●	●	●		●	●				●	●		●	●	●		●	●	●		●							
Felix Böttcher GmbH & Co. KG	●	●						●										●		●																	
Felix Schoeller Holding GmbH & Co. KG																		●	●																●		
FlexEnable Technology Ltd	●	●							●	●	●					●						●		●							●	●					
Flexoo GmbH									●	●	●	●		●	●	●	●		●		●					●	●		●	●					●		
Folex Coating GmbH										●			●	●	●			●			●	●	●														
Fontys University of Applied Sciences	●	●	●	●		●															●		●		●									●		
Fraunhofer Reserarch Institution for Microsystems and Solid State Technologies EMFT	●	●		●	●	●				●	●					●			●		●			●		●	●				●		●	●		
Fraunhofer ENAS	●	●	●	●			●		●	●	●			●		●			●		●					●	●					●	●	●	●	●	●
Fraunhofer FEP	●	●		●		●	●	●	●	●	●	●	●	●	●		●		●	●	●	●	●		●				●	●		●	●	●	●	●	●
Fraunhofer IAP	●	●	●	●					●	●	●		●	●	●		●	●	●		●	●	●	●	●	●			●	●		●	●	●	●	●	●
Fraunhofer IFAM	●	●	●		●				●	●	●	●		●	●		●		●		●					●			●	●			●	●	●	●	●
Fraunhofer ILT					●		●			●			●	●								●	●		●							●		●	●		
Fraunhofer IPA	●	●	●	●	●	●	●		●	●	●	●		●	●		●		●		●	●	●			●	●	●	●	●		●	●	●	●	●	●
Fraunhofer ISC			●	●																	●	●	●	●					●	●		●		●	●		
Fraunhofer ISE	●	●	●	●	●	●	●							●										●								●		●			
Friedrich Schiller University Jena	●	●	●							●	●		●	●		●			●		●	●	●	●			●										
Fundación Gaiker																																				
Fundacion Tekniker	●	●	●			●			●	●	●		●	●	●			●			●			●						●		●		●	●	●	
Genes´Ink	●	●	●		●				●	●	●	●	●	●	●		●		●	●	●	●	●	●		●			●	●	●	●		●	●	●	●
GraphenicaLab S.L.																																				
H.C. Moog Maschinen für Druck und Papier																		●	●																	
Hahn-Schickard-Gesellschaft für angewandte Forschung e.V.	●	●		●	●	●		●	●	●	●		●			●		●	●		●		●					●	●		●		●	●		
Henkel AG & Co.KGaA																																				
Heraeus Epurio GmbH	●	●	●	●					●	●	●	●	●				●	●			●	●	●	●	●	●			●	●							
Heraeus Printed Electronics GmbH																																				
Hochschule der Medien IAF, IAD	●	●	●			●		●	●	●	●		●	●			●	●	●		●	●			●	●					●	●		●	●	●	●
Hochschule München University of Applied Sciences	●	●		●	●				●	●	●	●		●			●	●	●		●	●				●			●	●		●	●	●	●	●	●
Hoffmann+Krippner GmbH	●			●	●	●		●	●	●	●							●	●	●	●					●					●				●		
Holst Centre	●	●		●			●	●	●	●	●	●	●	●	●		●				●	●	●						●	●		●		●	●	●	●
Hochschule Niederrhein																																				
Hummink	●	●								●								●			●	●		●											●	●	●
IBS Precision Engineering B.V.		●		●																																
IEE S.A. ZAE Weiergewan																																				
Imperial College London - Centre for Plastic Electronics																																				
Industrial Print Solutions GmbH																																				
Innovation Horizons GmbH											●	●		●	●						●			●	●				●	●	●	●	●			
Ino, d.o.o., Ziri									●	●	●	●	●	●	●	●	●	●	●		●			●	●	●		●	●							●
Institut für Mikroelektronik Stuttgart	●	●			●		●		●		●							●			●		●		●							●		●	●	●
Interlink Electronics, Inc.				●	●	●			●	●	●	●									●	●										●		●	●	●
IO Tech - Reophotonics																																				
IPC - Technical Centre of Plastics Engineering		●	●		●	●			●	●	●		●	●			●		●	●		●			●				●	●	●			●		●
IU Internationale Hochschule																																				

Products & Services Directory

OE-A members: J – R (1 of 2)

Categories: Region – Devices

www.oe-a.org

	Region					Core Competence							Substrates				
	Africa	Asia	Oceania	Europe	North America	Material supplier	Equipment manufacturer	Device manufacturer	Consulting & other services	End-user	R&D Institute	University	paper	plastic	metal	stainless steel	glass
Joanneum Research Forschungsgesellschaft mbH				●							●			●			●
Johannes Kepler Universität Linz - LIOS				●								●	●	●	●		●
Karlsruhe Institut für Technologie - LIT				●								●					
Kelenn Technology				●			●										
KETMarket GmbH				●					●								
KSG GmbH				●				●						●			
Leonhard Kurz Stiftung & Co. KG				●				●						●			
Landshut University of Applied Sciences				●								●		●			●
LC Elektronik sp. z o.o. sp. k.				●				●									
Lohmann GmbH & Co. KG				●		●											
Loughborough University				●								●	●	●	●		●
Luxembourg Institute of Science and Tech				●							●						
Max Planck Institut für Mikrostrukturphysik				●							●						
Mayr-Melnhof Packaging Premium Printing Center GmbH				●				●									
Merconics GmbH & Co. KG				●			●		●								
Metafas BV				●				●									
MGI - Ceradrop				●			●						●	●	●		●
Micromax (Deutschland) GmbH				●													
Mimotype Technologies GmbH				●		●											
Molecular Plasma Group				●			●		●				●	●	●	●	●
MSW				●					●				●	●			
NANO-C LLC					●	●											
National Research Council Canada					●						●		●	●			●
Naxnova Technologies Private Limited		●								●							
Neto Innovation				●					●								
New Cable Corporation				●				●						●			
Nexatech GmbH				●				●									
nextCoatema Technologies				●			●		●								
Normandy Coating				●			●						●	●			
nsm Norbert Schläfli AG				●			●										
NXT GmbH				●			●										
OLEDWorks				●				●									
Organic Electronic Technologies P.C.				●				●					●	●	●		●
Oulu University of Applied Sciences				●								●	●	●			
Piezotech S.A. S. Arkema-CRRA				●			●										
PolyIC GmbH & Co. KG				●				●						●			
PragmatIC Semiconductor Ltd.				●				●									
Printcolor Deutschland GmbH				●			●										
Printed Electronics Ltd.				●				●	●				●	●	●		●
Printegrica Inc.					●			●									
PROFACTOR GmbH				●							●			●			●
Pütz GmbH & Co. Folien KG				●			●							●			
PVF Mesh & Screen Technology GmbH				●				●									
RISE Research institutes of Sweden AB				●							●		●	●	●		
RK Siebdrucktechnik GmbH				●				●						●			
Robert Bosch Manufacturing Solutions Gmb				●				●									

oe-a PRODUCTS & SERVICES DIRECTORY

		Materials									Encapsulation					Equipment / Processes															Devices						
	textiles	other substrates	organic conductor	inorganic conductor / metal	p-type organic semiconductor	n-type organic semiconductor	inorganic semiconductor	dielectric	carbon nanotubes	graphene	other materials	thin film encapsulation	polymer film encapsulation	metal encapsulation	glass encapsulation	resins	other encapsulation	gravure printing	offset printing	flexographic printing	screen printing (flat bed)	inkjet printing	other printing	PVD - evaporation	PVD - sputtering	organic vapor phase deposition	spin coating	other coating (dip, blade, ...)	photolithography	laser ablation	laser transfer	encapsulation	clean room	ink formulation & manufacturing	dosing, metering & mixing of inks and fluids	other equipment / processes	transistors	memory elements	diodes	antennas	passives (e.g. capacitors, resistors)	integrated circuits (ICs)
Joanneum Research Forschungsgesellschaft mbH			●	●	●	●		●					●					●			●	●	●	●	●		●	●			●	●			●	●			●	●
Johannes Kepler Universität Linz - LIOS		●	●	●	●	●	●	●	●		●	●					●				●	●	●	●	●	●	●	●				●			●	●	●		●	●
Karlsruhe Institut für Technologie - LIT																		●				●					●	●	●				●			●					
Kelenn Technology																																									
KETMarket GmbH																																									
KSG GmbH											●		●			●	●				●						●	●	●				●			●			●	●	
Leonhard Kurz Stiftung & Co. KG				●														●		●	●		●	●						●	●					●				
Landshut University of Applied Sciences		●																			●												●			●					
LC Elektronik sp. z o.o. sp. k.																																									
Lohmann GmbH & Co. KG																																				●					
Loughborough University	●			●			●	●	●	●		●	●			●			●	●	●	●	●		●		●			●		●	●	●	●				●	
Luxembourg Institute of Science and Tech																																									
Max Planck Institut für Mikrostrukturphysik																																									
Mayr-Melnhof Packaging Premium Printing Center GmbH																																									
Merconics GmbH & Co. KG																						●	●																		
Metafas BV																																									
MGI - Ceradrop		●		●			●		●												●																●	●	●	
Micromax (Deutschland) GmbH																																									
Mimotype Technologies GmbH																																									
Molecular Plasma Group	●	●	●				●		●																	●		●							●						
MSW			●	●	●	●	●	●				●	●	●				●		●	●	●	●	●		●	●				●	●	●	●	●	●	●	●	●	●	●
NANO-C LLC						●			●												●	●		●		●								●		●	●	●	●		
National Research Council Canada	●		●	●	●	●	●	●				●	●					●	●	●	●	●	●			●		●	●							●		●	●	●	●
Naxnova Technologies Private Limited																																									
Neto Innovation																																									
New Cable Corporation																					●														●			●	●	
Nexatech GmbH																																									
nextCoatema Technologies																		●		●	●						●														
Normandy Coating	●	●																																								
nsm Norbert Schläfli AG												●	●	●	●	●	●	●	●	●	●	●					●					●			●					
NXT GmbH																																										
OLEDWorks																																									
Organic Electronic Technologies P.C.	●		●	●	●	●	●		●			●	●		●			●		●	●	●	●	●	●	●		●		●		●			●			●		
Oulu University of Applied Sciences				●			●											●		●	●	●																●	●		
Piezotech S.A. S. Arkema-CRRA							●		●																												●				
PolyIC GmbH & Co. KG				●	●	●	●	●			●	●	●				●	●			●		●				●	●	●				●	●		●	●	●	●		●	●
PragmatIC Semiconductor Ltd.				●			●	●			●	●	●								●	●	●	●	●		●		●	●	●	●	●			●	●	●	●	●	●
Printcolor Deutschland GmbH																																									
Printed Electronics Ltd.	●	●	●	●				●		●	●										●	●	●					●			●	●	●	●	●			●	●	●
Printegrica Inc.																																									
PROFACTOR GmbH	●		●	●				●		●					●	●						●	●		●	●	●	●				●			●			●	●	●
Pütz GmbH & Co. Folien KG										●	●																														
PVF Mesh & Screen Technology GmbH																																									
RISE Research institutes of Sweden AB				●	●	●		●	●			●	●			●		●		●	●		●	●		●		●	●			●				●		●	●	●	●
RK Siebdrucktechnik GmbH																		●	●	●	●	●					●														
Robert Bosch Manufacturing Solutions Gmb																																									

Products & Services Directory

OE-A members: J – R (2 of 2)

Categories: Devices – Education

www.oe-a.org

	Devices												Integration				
	OLEDs	electrochromic displays	electrophoretic displays	electroluminescence	bioluminescence	other display technologies	touch screens / surfaces	sensors (devices)	photovoltaic cells	OPV - organic photovoltaic cells	batteries	other devices	hybrid systems	electrical contacting (e.g. flip-chip)	lamination	integration into packaging	other (integration)
Joanneum Research Forschungsgesellschaft mbH							●	●				●					●
Johannes Kepler Universität Linz - LIOS	●	●	●	●		●	●	●	●		●						
Karlsruhe Institut für Technologie - LIT	●								●		●						
Kelenn Technology																	
KETMarket GmbH																	
KSG GmbH	●	●		●										●	●	●	
Leonhard Kurz Stiftung & Co. KG		●				●	●		●						●		●
Landshut University of Applied Sciences				●									●	●		●	
LC Elektronik sp. z o.o. sp. k.																	
Lohmann GmbH & Co. KG															●		●
Loughborough University				●				●			●	●		●		●	
Luxembourg Institute of Science and Tech																	
Max Planck Institut für Mikrostrukturphysik																	
Mayr-Melnhof Packaging Premium Printing Center GmbH																	
Merconics GmbH & Co. KG																	
Metafas BV																	
MGI - Ceradrop								●	●		●						
Micromax (Deutschland) GmbH																	
Mimotype Technologies GmbH																	
Molecular Plasma Group																	●
MSW	●	●	●	●		●	●	●			●	●	●	●	●	●	
NANO-C LLC							●		●	●	●						
National Research Council Canada	●			●		●		●	●				●		●	●	
Naxnova Technologies Private Limited																	
Neto Innovation																	
New Cable Corporation															●		
Nexatech GmbH																	
nextCoatema Technologies																	
Normandy Coating																	
nsm Norbert Schläfli AG													●		●		
NXT GmbH																	
OLEDWorks	●			●		●											
Organic Electronic Technologies P.C.	●	●						●	●		●						
Oulu University of Applied Sciences		●						●									
Piezotech S.A. S. Arkema-CRRA								●				●					
PolyIC GmbH & Co. KG		●				●	●	●	●			●	●	●	●	●	●
PragmatIC Semiconductor Ltd.								●				●		●	●	●	●
Printcolor Deutschland GmbH																	
Printed Electronics Ltd.	●	●		●			●	●			●	●	●	●		●	
Printegrica Inc.																	
PROFACTOR GmbH			●					●	●								
Pütz GmbH & Co. Folien KG												●					
PVF Mesh & Screen Technology GmbH																	
RISE Research institutes of Sweden AB		●		●			●	●			●						
RK Siebdrucktechnik GmbH																	
Robert Bosch Manufacturing Solutions Gmb																	

oe-a PRODUCTS & SERVICES DIRECTORY

	Testing								Applications by Industry										Applications											Other Services				Education		
	electrical characterization	physical/optical characterization	chemical characterization	lifetime	quality / process control	environmental testing	simulation / circuit optimization	other tests	automotive	consumer electronics	healthcare, medical and pharmaceutical	sports goods, wellbeing	lighting (applications by industry)	energy	building and architecture	retail and logistics	textiles and fashion	printing and graphic arts	packaging	other applications by industry	sensors (applications)	displays	lighting (applications)	transistors	solar cells	smart objects (e.g. smart cards, games, gadgets)	RFID	speakers	smart textiles	wearables	other applications	technical consulting	business consulting	management of R&D funding programs	research and development	Bachelor/Master Thesis	PhD Thesis	Internship
Joanneum Research Forschungsgesellschaft mbH	●	●	●		●				●	●	●			●	●		●	●	●		●			●		●				●	●			●			
Johannes Kepler Universität Linz - LIOS	●	●	●	●		●	●							●							●	●	●	●	●	●					●			●			
Karlsruhe Institut für Technologie - LIT	●	●						●													●					●					●				●			
Kelenn Technology																																						
KETMarket GmbH																																						
KSG GmbH	●	●	●	●	●		●		●	●	●		●	●						●	●	●	●				●				●	●			●			
Leonhard Kurz Stiftung & Co. KG	●	●	●	●	●	●			●	●	●		●		●	●	●	●	●	●	●	●	●		●	●	●				●				●			
Landshut University of Applied Sciences	●						●															●				●			●	●					●	●		●
LC Elektronik sp. z o.o. sp. k.																																						
Lohmann GmbH & Co. KG									●	●	●			●	●			●														●				●		●
Loughborough University	●	●	●	●		●				●	●	●	●	●			●	●	●	●	●	●	●		●	●	●		●	●		●		●	●	●	●
Luxembourg Institute of Science and Tech																																						
Max Planck Institut für Mikrostrukturphysik																																						
Mayr-Melnhof Packaging Premium Printing Center GmbH																																						
Merconics GmbH & Co. KG																																	●			●		
Metafas BV																																						
MGI - Ceradrop		●	●		●				●	●	●			●				●			●		●	●	●	●				●		●	●				
Micromax (Deutschland) GmbH																																						
Mimotype Technologies GmbH																																						
Molecular Plasma Group									●	●	●	●	●		●		●	●	●	●	●	●	●	●		●		●	●	●	●	●			●			
MSW	●	●	●	●	●	●	●		●	●	●	●	●	●	●	●	●	●		●	●	●	●	●		●	●	●	●	●	●	●	●	●	●			
NANO-C LLC	●		●		●				●	●				●	●		●	●		●			●	●										●	●	●	●	●
National Research Council Canada	●	●	●	●	●	●	●			●	●	●		●	●	●	●	●		●	●	●	●	●		●	●	●	●	●	●	●		●		●	
Naxnova Technologies Private Limited																																						
Neto Innovation										●	●	●	●	●	●		●	●		●		●		●		●			●	●	●	●		●	●			
New Cable Corporation				●		●			●	●	●									●	●							●			●	●			●	●		
Nexatech GmbH																																						
nextCoatema Technologies									●	●	●	●	●	●	●	●	●	●		●	●	●	●	●		●	●	●	●	●		●			●			
Normandy Coating									●	●	●	●		●	●	●	●	●		●	●	●		●		●		●	●	●								
nsm Norbert Schläfli AG				●	●		●		●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●		●	●	●	●	●	●	●			●			
NXT GmbH		●		●					●	●			●									●		●														
OLEDWorks									●	●	●		●		●	●						●	●							●						●	●	
Organic Electronic Technologies P.C.	●	●		●		●			●	●	●		●	●	●		●	●	●		●	●	●	●	●	●		●			●	●	●	●			
Oulu University of Applied Sciences	●				●						●					●			●		●														●	●		●
Piezotech S.A. S. Arkema-CRRA	●								●	●	●	●			●				●	●	●			●			●			●	●							
PolyIC GmbH & Co. KG	●	●		●	●	●	●	●																														
PragmatIC Semiconductor Ltd.	●	●		●	●	●	●									●			●	●	●			●		●		●				●						
Printcolor Deutschland GmbH																																						
Printed Electronics Ltd.	●			●	●	●			●	●	●	●	●	●	●		●	●	●	●	●	●	●		●	●	●	●	●	●	●	●	●	●	●			
Printegrica Inc.																																						
PROFACTOR GmbH		●	●		●						●	●	●				●	●	●		●	●		●	●	●	●		●					●	●		
Pütz GmbH & Co. Folien KG									●	●	●			●				●	●		●	●	●		●	●		●				●						
PVF Mesh & Screen Technology GmbH																																						
RISE Research institutes of Sweden AB	●		●	●	●	●	●				●				●			●	●		●	●		●		●					●	●	●	●			
RK Siebdrucktechnik GmbH									●	●	●		●	●	●		●	●	●													●			●			
Robert Bosch Manufacturing Solutions Gmb																																						

oe-a PRODUCTS & SERVICES DIRECTORY

Products & Services Directory

OE-A members: S – Z (1 of 2)

Categories: Region – Devices

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	Region					Core Competence							Substrates				
	Africa	Asia	Oceania	Europe	North America	Material supplier	Equipment manufacturer	Device manufacturer	Consulting & other services	End-user	R&D Institute	University	paper	plastic	metal	stainless steel	glass
SAES Getters S.p.A.				●		●								●	●	●	●
SAIT Europe Samsung Advanced Institute of Technology				●						●				●	●		●
Saralon GmbH				●		●							●	●			●
Screentec Oy				●				●					●	●			●
Seristampa Srl				●				●									
Silicon Austria Labs GmbH				●							●		●	●	●	●	●
SmartKem Limited				●		●											
SpeedPox GmbH				●		●											
Spin Corporation		●					●										
SPS TechnoScreen GmbH					●	●											
Suzhou Institute of Nano-Tech and Nano-Bionics, CAS		●									●						
Suzhou Leanstar Technology Co., Ltd																	
Symbio				●				●									
Tacterion GmbH				●				●						●			
TactoTek Oy				●				●									
Tampere University of Technology				●								●	●	●			●
Technische Hochschule Nürnberg Georg Simon Ohm				●								●	●	●			
Technische Universität Chemnitz				●								●	●	●			●
Technische Universität Dresden - IAPP				●								●		●	●		●
tesa SE				●			●										
TracXon B.V.				●				●									
TSE Troller AG				●					●								
UDC Ventures					●		●										
University of West Bohemia in Pilsen				●								●	●	●			●
University of Bordeaux 1 LCPO-UMB5629				●								●		●			
University of Erlangen				●								●					
University Luxembourg				●								●					
University of Novi Sad				●								●	●	●			●
University of Pardubice				●								●	●	●			●
Universitat Politècnica de València				●								●	●	●			●
VFP Ink Technologies				●					●								
VITO NV				●							●						
VTT-Technical Research Centre of Finland				●							●						
WCPC Swansea University				●								●	●	●	●		●
Werner Blase GmbH & Co KG				●				●									
WESTRA Materials				●			●										
Witte Technology GmbH				●				●						●			●
XTPL S.A.				●					●								
Yamagata University		●									●	●	●	●			●
Ynvisible Interactiv Inc.					●			●									
Zhejiang Brilliant Optoelectronic Techno		●					●										

	Materials										Encapsulation						Equipment / Processes																					Devices							
	textiles	other substrates	organic conductor	inorganic conductor / metal	p-type organic semiconductor	n-type organic semiconductor	inorganic semiconductor	dielectric	carbon nanotubes	graphene	other materials	thin film encapsulation	polymer film encapsulation	metal encapsulation	glass encapsulation	resins	other encapsulation	gravure printing	offset printing	flexographic printing	screen printing (flat bed)	inkjet printing	other printing	PVD - evaporation	PVD - sputtering	organic vapor phase deposition	spin coating	other coating (dip, blade, ...)	photolithography	laser ablation	laser transfer	encapsulation	clean room	ink formulation & manufacturing	dosing, metering & mixing of inks and fluids	other equipment / processes	transistors	memory elements	diodes	antennas	passives (e.g. capacitors, resistors)	integrated circuits (ICs)
SAES Getters S.p.A.					●	●		●				●	●	●	●	●	●					●					●	●				●	●	●		●						
SAIT Europe Samsung Advanced Institute of Technology		●	●	●	●	●	●	●	●	●	●													●	●	●										●	●	●	●	●	●	●
Saralon GmbH	●		●	●				●			●									●	●															●	●	●	●		●
Screentec Oy	●	●	●					●			●						●				●											●	●		●						
Seristampa Srl																																										
Silicon Austria Labs GmbH	●		●	●				●	●	●			●			●					●	●					●	●		●		●	●		●				●	●	●
SmartKem Limited					●			●																												●						
SpeedPox GmbH																																										
Spin Corporation																		●	●		●	●																				
SPS TechnoScreen GmbH								●		●	●					●		●		●	●	●												●						●	●	
Suzhou Institute of Nano-Tech and Nano-Bionics, CAS																																										
Suzhou Leanstar Technology Co., Ltd																																										
Symbio																																										
Tacterion GmbH			●	●				●			●	●	●				●				●											●									
TactoTek Oy																																										
Tampere University of Technology	●		●	●	●	●	●	●			●	●	●					●		●	●		●		●	●					●	●	●		●		●	●	●	●
Technische Hochschule Nürnberg Georg Simon Ohm				●																	●	●		●			●					●			●					
Technische Universität Chemnitz	●		●	●	●			●	●	●								●		●	●	●					●						●		●		●		●	
Technische Universität Dresden - IAPP				●	●	●		●				●	●	●	●	●	●							●	●	●	●		●		●	●				●	●	●		●	●
tesa SE																																										
TracXon B.V.																																										
TSE Troller AG																											●								●						
UDC Ventures			●																			●		●																		
University of West Bohemia in Pilsen	●	●	●	●				●	●		●										●	●					●	●	●			●				●			●	●	
University of Bordeaux 1 LCPO-UMB5629			●		●	●		●			●		●			●					●	●	●	●	●	●	●	●			●	●	●		●	●	●		●	
University of Erlangen																																										
University Luxembourg																																										
University of Novi Sad				●	●		●	●		●			●			●	●		●	●		●																●		●	●
University of Pardubice	●		●	●			●	●	●		●	●							●	●	●	●					●									●			●	●	
Universitat Politècnica de València	●		●	●				●					●								●						●									●				●	
VFP Ink Technologies				●				●	●	●																								●								
VITO NV																																										
VTT-Technical Research Centre of Finland													●	●		●		●		●	●	●	●	●	●	●	●	●	●			●	●	●	●	●	●		●	●	
WCPC Swansea University	●	●							●	●	●							●	●	●	●	●					●												●	●	
Werner Blase GmbH & Co KG																																										
WESTRA Materials																																										
Witte Technology GmbH		●	●	●			●	●	●	●	●	●	●	●		●	●		●	●	●	●								●	●	●	●		●		●	●	●	●
XTPL S.A.																																										
Yamagata University			●	●	●	●		●	●		●	●	●				●	●	●	●	●	●	●			●	●	●			●		●			●	●	●	●	●	●
Ynvisible Interactiv Inc.										●																																
Zhejiang Brilliant Optoelectronic Techno																																										

oe-a PRODUCTS & SERVICES DIRECTORY

Products & Services Directory

OE-A members: S – Z (2 of 2)

Categories: Devices – Education

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	Devices													Integration				
	OLEDs	electrochromic displays	electrophoretic displays	electroluminescence	bioluminescence	other display technologies	touch screens / surfaces	sensors (devices)	photovoltaic cells	OPV - organic photovoltaic cells	batteries	other devices	hybrid systems	electrical contacting (e.g. flip-chip)	lamination	integration into packaging	other (integration)
SAES Getters S.p.A.	●	●	●	●		●		●	●	●	●	●					
SAIT Europe Samsung Advanced Institute of Technology	●	●	●	●		●	●	●	●		●	●		●	●	●	●
Saralon GmbH	●	●		●				●			●	●	●	●	●	●	●
Screentec Oy							●	●					●			●	
Seristampa Srl																	
Silicon Austria Labs GmbH	●	●		●				●		●	●		●	●	●	●	
SmartKem Limited																	
SpeedPox GmbH																	
Spin Corporation																	
SPS TechnoScreen GmbH				●		●	●		●								
Suzhou Institute of Nano-Tech and Nano-Bionics, CAS																	
Suzhou Leanstar Technology Co., Ltd																	
Symbio																	
Tacterion GmbH								●					●		●		●
TactoTek Oy																	
Tampere University of Technology							●	●					●	●		●	
Technische Hochschule Nürnberg Georg Simon Ohm								●						●		●	
Technische Universität Chemnitz		●						●	●				●		●		
Technische Universität Dresden - IAPP	●			●				●	●			●		●	●		
tesa SE																	
TracXon B.V.																	
TSE Troller AG												●					
UDC Ventures	●																
University of West Bohemia in Pilsen								●					●	●			
University of Bordeaux 1 LCPO-UMB5629	●	●	●	●			●	●	●								
University of Erlangen																	
University Luxembourg																	
University of Novi Sad	●							●									
University of Pardubice		●		●				●	●								
Universitat Politècnica de València		●									●		●				
VFP Ink Technologies																	
VITO NV																	
VTT-Technical Research Centre of Finland	●			●		●	●	●	●	●	●	●	●	●	●	●	●
WCPC Swansea University				●				●	●			●					
Werner Blase GmbH & Co KG																	
WESTRA Materials																	
Witte Technology GmbH	●	●	●	●		●	●	●	●	●	●	●	●		●	●	●
XTPL S.A.																	
Yamagata University								●			●		●			●	
Ynvisible Interactiv Inc.		●															
Zhejiang Brilliant Optoelectronic Techno																	

	Testing								Applications by Industry										Applications											Other Services				Education		
	electrical characterization	physical/optical characterization	chemical characterization	lifetime	quality / process control	environmental testing	simulation / circuit optimization	other tests	automotive	consumer electronics	healthcare, medical and pharmaceutical	sports goods, wellbeing	lighting (applications by industry)	energy	building and architecture	retail and logistics	textiles and fashion	printing and graphic arts	packaging	other applications by industry	sensors (applications)	displays	lighting (applications)	transistors	solar cells	smart objects (e.g. smart cards, games, gadgets)	RFID	speakers	smart textiles	wearables	other applications	technical consulting	business consulting	management of R&D funding programs	research and development	Bachelor/Master Thesis	PhD Thesis	Internship
SAES Getters S.p.A.		●	●	●					●	●	●		●	●					●		●	●	●	●	●					●							
SAIT Europe Samsung Advanced Institute of Technology	●	●	●	●	●	●	●	●		●											●	●		●			●	●		●				●			
Saralon GmbH	●	●	●	●	●	●	●	●	●	●	●	●	●			●	●	●	●	●	●	●	●	●		●	●			●	●	●	●	●			
Screentec Oy									●	●	●	●					●	●	●	●	●					●	●			●	●	●	●	●			
Seristampa Srl																																					
Silicon Austria Labs GmbH	●	●	●				●		●	●	●	●	●	●	●	●	●		●		●		●		●	●	●		●	●		●		●	●	●
SmartKem Limited																						●		●													
SpeedPox GmbH																																					
Spin Corporation																		●			●	●		●	●					●	●	●				
SPS TechnoScreen GmbH									●	●	●	●	●				●	●	●		●	●	●		●		●			●	●	●			●	●	
Suzhou Institute of Nano-Tech and Nano-Bionics, CAS																																					
Suzhou Leanstar Technology Co., Ltd																																					
Symbio																																					
Tacterion GmbH	●	●		●	●				●	●	●	●				●	●			●	●					●				●	●	●	●		●		●
TactoTek Oy																																					
Tampere University of Technology	●	●				●	●		●	●	●	●		●	●	●	●	●	●		●			●	●	●	●		●	●			●	●	●	●
Technische Hochschule Nürnberg Georg Simon Ohm	●	●		●		●															●					●					●			●			
Technische Universität Chemnitz	●	●							●				●				●	●			●		●	●	●	●			●		●			●	●	●	●
Technische Universität Dresden - IAPP	●	●	●	●	●	●	●														●	●	●	●	●									●			
tesa SE																																					
TracXon B.V.																																					
TSE Troller AG																						●	●		●		●		●					●			
UDC Ventures									●	●		●										●	●		●												
University of West Bohemia in Pilsen	●	●			●	●	●			●	●				●		●		●		●			●			●		●	●		●		●	●	●
University of Bordeaux 1 LCPO-UMB5629	●	●	●																		●	●	●	●	●				●			●	●	●	●	●
University of Erlangen																																					
University Luxembourg																																					
University of Novi Sad	●	●					●		●	●									●		●						●			●	●			●			
University of Pardubice		●	●		●	●												●			●	●		●					●					●			
Universitat Politècnica de València		●		●						●	●						●	●	●		●		●						●					●	●	●
VFP Ink Technologies									●	●	●	●	●	●	●	●	●	●	●	●	●	●		●	●	●	●	●	●	●						●	
VITO NV																															●	●	●	●	●	●	●
VTT-Technical Research Centre of Finland	●	●	●	●	●	●	●		●	●	●	●	●	●		●			●		●		●	●	●	●		●	●		●			●			
WCPC Swansea University		●			●	●			●	●	●		●	●	●		●	●	●	●	●		●		●	●		●		●				●			
Werner Blase GmbH & Co KG																																					
WESTRA Materials																																					
Witte Technology GmbH	●	●		●	●		●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●	●		●	●	●	●			●	●		●
XTPL S.A.																																					
Yamagata University	●	●		●			●														●	●		●		●			●						●	●	●
Ynvisible Interactiv Inc.										●	●	●				●		●	●	●		●				●					●			●	●	●	●
Zhejiang Brilliant Optoelectronic Techno																																					